



Click [here](#) for the 3D model.

General Information

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|-------------|--|
| Series | Array Comm COG Flex |
| Style | SMD Array |
| Description | SMD, MLCC, Array, Flex Termination, Class II |
| RoHS | Yes |
| Termination | Flexible Termination |
| AEC-Q200 | No |
| Chip Size | 0612 |
| MSL | 1 |

Dimensions

| | |
|---|-----------------|
| L | 1.6mm +/-0.2mm |
| W | 3.2mm +/-0.2mm |
| T | 0.8mm +/-0.10mm |
| P | 0.8mm +/-0.10mm |

Packaging Specifications

| | |
|--------------------|------------------------|
| Packaging | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000 |

Specifications

| | |
|-----------------------|--------------------|
| Capacitance | 330 pF |
| Tolerance | 5% |
| Voltage DC | 50 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Insulation Resistance | 100 GOhms |